

## **ABSTRACT OF THE DISCLOSURE**

Methods of manufacturing lead frame connectors for use in connecting optical sub-assemblies to printed circuit boards in optical transceiver modules. The lead frame connectors are formed by first stamping a selected configuration of conductors in a conductive ribbon. The conductors are bent as necessary and passed in a reel-to-reel manner through an insert injection molding process to form an electrically insulating casing about the conductors. After the molding process, the ribbon is singulated to obtain individual lead frame connectors. The individual conductors encased in the casing can be electrically separated by punching out a connecting conductive structure through a hole formed in the casing. The connecting conductive structure mechanically secures the conductors to each other during the molding process and, when punched out, substantially eliminate stubs that could otherwise degrade the RF performance of the lead frame connectors.

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